SLOVENSKI STANDARD
SIST EN 62047-25:2017

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Polprevodniški elementi - Mikroelektromehanski elementi - 25. del: Tehnologija proizvodnje MEMS na siliciju - Metoda za merjenje potezno-potisne in strižne trdnosti mikro spojnih mest (IEC 62047-25:2016)

Semiconductor devices - Micro-electromechanical devices - Part 25: Silicon-based MEMS fabrication technology - Measurement method of pull-press and shearing strength of micro bonding area (IEC 62047-25:2016)

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31.080.01	Polprevodniški elementi (naprave) na splošno	Semiconductor devices in general

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EUROPEAN STANDARD

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English Version

Semiconductor devices - Micro-electromechanical devices - Part 25: Silicon based MEMS fabrication technology - Measurement method of pull-press and shearing strength of micro bonding area (IEC 62047-25:2016)

Dispositifs à semiconducteurs - Dispositifs microélectromécaniques - Partie 25: Technologie de fabrication de MEMS à base de silicium - Méthode de mesure de la résistance à la traction-compression et au cisaillement d'une micro zone de brasure (IEC 62047-25:2016)

Halbleiterbauelemente - Bauelemente der Mikrosystemtechnik - Teil 25: Siliziumbasierte MEMS-Herstellungstechnologie - Messverfahren zur Zug-Druck- und Scherfestigkeit gebondeter Flächen im Mikrometerbereich (IEC 62047-25:2016)

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European foreword

The text of document 47F/249/FDIS, future edition 1 of IEC 62047-25, prepared by SC 47F "Microelectromechanical systems" of IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62047-25:2016.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2017-07-03
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Annex ZA
(normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu

Publication	Year	Title	EN/HD	Year
IEC 62047-1	-	Semiconductor devices - Micro-electromechanical devices - Part 1: Terms and definitions	EN 62047-1	-
ISO 10012	-	Measurement management systems - Requirements for measurement processes and measuring equipment	EN ISO 10012	-

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Semiconductor devices – Micro-electromechanical devices – Part 25: Silicon based MEMS fabrication technology – Measurement method of pull-press and shearing strength of micro bonding area

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Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

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